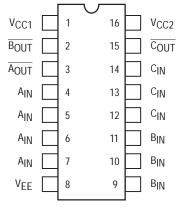
Triple 4-3-3-Input Bus Driver

The MC10123 consists of three NOR gates designed for bus driving applications on card or between cards. Output low logic levels are specified with $V_{OL} = -2.1$ Vdc so that the bus may be terminated to -2.0 Vdc. The gate output, when low, appears as a high impedance to the bus, because the output emitter– followers of the MC10123 are "turned–off." This eliminates discontinuities in the characteristic impedance of the bus.

The V_{OH} level is specified when driving a 25–ohm load terminated to -2.0 Vdc, the equivalent of a 50–ohm bus terminated at both ends. Although 25 ohms is the lowest characteristic impedance that can be driven by the MC10123, higher impedance values may be used with this part. A typical 50–ohm bus is shown in Figure 1.

- $P_D = 310 \text{ mW typ/pkg (No Load)}$
- $t_{pd} = 3.0 \text{ ns typ}$
- t_r , $t_f = 2.5$ ns typ (20%–80%)

DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.

For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



ON Semiconductor

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MARKING DIAGRAMS



CDIP-16 L SUFFIX CASE 620 MC10123L AWLYYWW



PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping		
MC10123L	CDIP-16	25 Units / Rail		
MC10123P	PDIP-16	25 Units / Rail		
MC10123FN	PLCC-20	46 Units / Rail		

LOGIC DIAGRAM

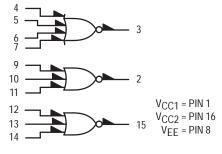
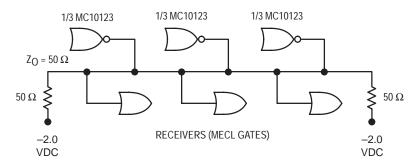


FIGURE 1 — 50-OHM BUS DRIVER (TYPICAL APPLICATION)



MC10123

ELECTRICAL CHARACTERISTICS

				Test Limits							
			Pin Under	−30°C		+25°C			+85°C		1
Characteristic		Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	Unit
Power Supply	Drain Current	ΙE	8		82		71	75		82	mAdc
Input Current		l _{inH}	4		350			220		220	μAdc
		l _{inL}	4			0.5					μAdc
Output Voltage	Logic 1	Vон	3	-1.060	-0.890	-0.960		-0.810	-0.890	-0.700	Vdc
Output Voltage	Logic 0	VOL	3	-2.100	-2.030	-2.100		-2.030	-2.100	-2.030	Vdc
Threshold Volta	age Logic 1	Vона	3	-1.080		-0.980			-0.910		Vdc
Threshold Volta	age Logic 0	VOLA	3		-2.100			-2.100		-2.100	Vdc
Switching Time	es (50Ω Load)										ns
Propagation Do	elay	t ₄₊₃ _ t ₄₋₃₊	3 3	1.2 1.2	4.6 4.6	1.2 1.2	3.0 3.0	4.4 4.4	1.2 1.2	4.8 4.8	
Rise Time	(20 to 80%)	t3+	3	1.0	3.7	1.0	2.5	3.5	1.0	3.9	
Fall Time	(20 to 80%)	t3_	3	1.0	3.7	1.0	2.5	3.5	1.0	3.9	

ELECTRICAL CHARACTERISTICS (continued)

					TEST VO	LTAGE VALU	JES (Volts)		
		@ Test Te	mperature	V _{IHmax}	V _{ILmin}	V _{IHAmin}	V _{ILAmax}	VEE	1
			-30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
			+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
			+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	1
	TEST VOLTAGE APPLIED TO PINS LISTED BELOW					, , ,			
Characteristic		Symbol	Under Test	V _{IHmax}	V _{ILmin}	VIHAmin	V _{ILAmax}	VEE	(VCC) Gnd
Power Supply Drain Current		ΙE	8	4,5,6,7,9 10,11,12 13,14				8	1, 16
Input Current		linH	4	4				8	1, 16
		l _{inL}	4		4			8	1, 16
Output Voltage	Logic 1	Voн	3					8	1, 16
Output Voltage	Logic 0	VOL	3	4,5,6,7 9,12				8	1, 16
Threshold Voltage	Logic 1	Vона	3				4,5,6,7	8	1, 16
Threshold Voltage	Logic 0	Vola	3	9,12		4,5,6,7		8	1, 16
Switching Times	(50Ω Load)					Pulse In	Pulse Out	-3.2 V	+2.0 V
Propagation Delay		t ₄₊₃₋ t ₄₋₃₊	3 3			4 4	3 3	8 8	1, 16 1, 16
Rise Time	(20 to 80%)	t3+	3			4	3	8	1, 16
Fall Time	(20 to 80%)	t3_	3			4	3	8	1, 16

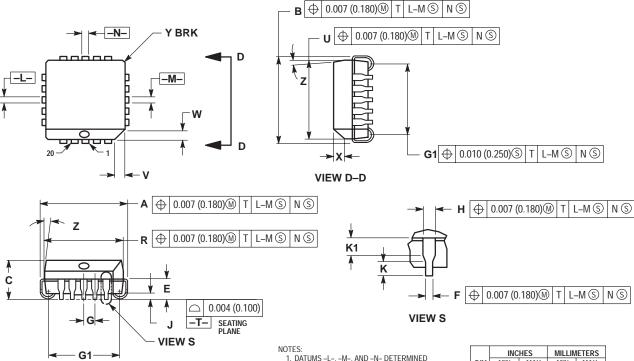
Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50-ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

MC10123

PACKAGE DIMENSIONS

PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

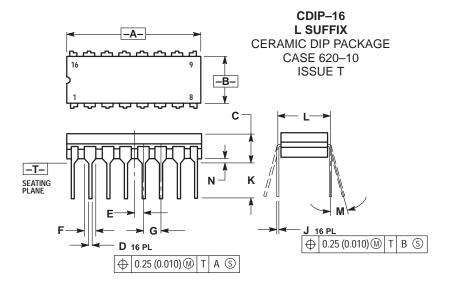
- DATUMS -L-, -M-, AND -N- DETERMINED
 WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTRA FRAST BODY AT MOLD PARTING LINE.

 2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

 3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

_					
	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.385	0.395	9.78	10.03	
В	0.385	0.395	9.78	10.03	
С	0.165	0.180	4.20	4.57	
Ε	0.090	0.110	2.29	2.79	
F	0.013	0.019	0.33	0.48	
G	0.050	BSC	1.27	BSC	
Н	0.026	0.032	0.66	0.81	
J	0.020		0.51		
K	0.025		0.64		
R	0.350	0.356	8.89	9.04	
U	0.350	0.356	8.89	9.04	
٧	0.042	0.048	1.07	1.21	
W	0.042	0.048	1.07	1.21	
Χ	0.042	0.056	1.07	1.42	
Υ		0.020		0.50	
Z	2°	10 °	2 °	10 °	
G1	0.310	0.330	7.88	8.38	
K1	0.040		1.02		

MC10123

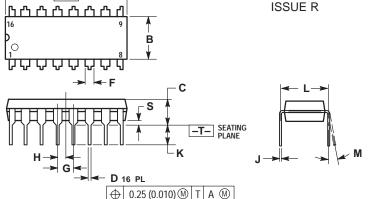


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN
- FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030) WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIMETERS		
DIM	MIN	MIN MAX		MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54 BSC		
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300 BSC		7.62	BSC	
M	0°	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIMETERS		
DIM	MIN MAX		MIN	MAX	
Α	0.740	0.740 0.770		19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0 °	10 °	
S	0.020 0.040		0.51	1.01	

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